

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A polishing body, comprising:

a polishing part with a predetermined shape comprising an abrasive dispersed in a matrix material molded from a residue or a dried powder;

said residue or dried powder being prepared by eliminating a dispersion medium from an aqueous dispersion comprising a matrix material and abrasive.

Claim 2 (Currently Amended): The polishing body according to Claim 1, wherein a ~~method for eliminating of~~ said dispersion medium is eliminated by ~~is a~~ spray drying ~~method~~.

Claim 3 (Currently Amended): The polishing body according to Claim 1, wherein the polishing body is ~~used~~ adapted for the polishing of semiconductors.

Claim 4 (Currently Amended): A polishing body, comprising:

a polishing part with a predetermined shape molded from a residue or a dried powder;

said residue or dried powder being prepared by eliminating a dispersion medium from an aqueous dispersion comprising dispersed composite particles comprising an abrasive attached to a matrix material,

said abrasive being dispersed in said matrix material.

Claim 5 (Currently Amended): The polishing body according to Claim 4, wherein a ~~method for eliminating of~~ said dispersion medium is a eliminated by spray drying ~~method~~.

Claim 6 (Previously Presented): The polishing body according to Claim 4, wherein said aqueous dispersion further comprises a matrix material and/or an abrasive.

Claim 7 (Original) The polishing body according to Claim 4, wherein the respective zeta potentials of said matrix material and said abrasive are opposite in sign and the difference of said zeta potentials is 5mV or more.

Claim 8 (Currently Amended): The polishing body according to Claim 4, wherein the polishing body is ~~used~~ adapted for the polishing of semiconductors.

Claim 9 (Currently Amended): A polishing body, comprising:
a polishing part with a predetermined shape comprising an abrasive dispersed in a matrix material comprising crosslinked polymer molded from a residue or a dried powder;
said residue or dried powder being prepared by eliminating a dispersion medium from an aqueous dispersion ~~containing~~ comprising 1) a matrix material comprising a crosslinkable polymer and 2) an abrasive,
said crosslinkable polymer being crosslinked during ~~eliminating~~ elimination of said dispersion medium, or during molding, or after molding, thereby obtaining a crosslinked structure.

Claim 10 (Currently Amended): The polishing body according to Claim 9, wherein a ~~method for eliminating of~~ said dispersion medium is a eliminated by spray drying method.

Claim 11 (Currently Amended): The polishing body according to Claim 9, wherein the polishing body is ~~used~~ adapted for the polishing of semiconductors.

Claim 12 (Currently Amended): A polishing body, comprising:
a polishing part with a predetermined shape molded from a residue or a dried powder;
said residue or dried powder being prepared by eliminating a dispersion medium from an aqueous dispersion ~~containing~~ comprising dispersed composite particles comprising an abrasive attached to a matrix material, said matrix material comprising a crosslinkable polymer,
said crosslinkable polymer being crosslinked during ~~eliminating~~ elimination of said dispersion medium, or during molding, or after molding, thereby obtaining a crosslinked structure, and
said abrasive being dispersed in said matrix material.

Claim 13 (Currently Amended): The polishing body according to Claim 12, wherein ~~a method for eliminating of~~ said dispersion medium is eliminated by a spray drying ~~method~~.

Claim 14 (Original) The polishing body according to Claim 12, wherein the respective zeta potentials of said matrix material and said abrasive are opposite in sign and the difference of said zeta potentials is 5mV or more.

Claim 15 (Currently Amended): The polishing body according to Claim 12, wherein the polishing body is ~~used~~ adapted for the polishing of semiconductors.

Claims 16 - 19 (Canceled).

Claim 20 (Previously Presented): A polishing pad, which comprises the polishing body according to Claim 1.

Claim 21 (Previously Presented): A polishing pad, which comprises the polishing body according to Claim 4.

Claim 22 (Previously Presented): A polishing pad, which comprises the polishing body according to Claim 9.

Claim 23 (Previously Presented): A polishing pad, which comprises the polishing body according to Claim 12.

Claim 24 (Previously Presented): A method for polishing of semiconductors, comprising:

polishing a semiconductor with the polishing body according to Claim 1.

Claim 25 (Previously Presented): A method for polishing of semiconductors, comprising:

polishing a semiconductor with the polishing body according to Claim 4.

Claim 26 (Previously Presented): A method for polishing of semiconductors, comprising:

polishing a semiconductor with the polishing body according to Claim 9.

Claim 27 (Previously Presented): A method for polishing of semiconductors, comprising:

polishing a semiconductor with the polishing body according to Claim 12.

Claim 28 (New): A polishing body, comprising:

a polishing part with a predetermined shape molded from a residue or a dried powder;

said residue or dried powder being prepared by eliminating a dispersion medium from an aqueous dispersion comprising dispersed composite particles comprising an abrasive attached to a matrix material

wherein the respective zeta potentials of said matrix material and said abrasive are opposite in sign and the difference of said zeta potentials is 5mV or more.

Claim 29 (New): The polishing body according to Claim 28, wherein said dispersion medium is eliminated by spray drying.

Claim 30 (New): The polishing body according to Claim 28, wherein said aqueous dispersion further comprises a matrix material and/or an abrasive.

Claim 31 (New): The polishing body according to Claim 28, wherein the polishing body is adapted for the polishing of semiconductors.

Claim 32 (New): A polishing body, comprising:

a polishing part with a predetermined shape molded from a residue or a dried powder;

said residue or dried powder being prepared by eliminating a dispersion medium from an aqueous dispersion containing dispersed composite particles comprising an abrasive attached to a matrix material, said matrix material comprising a crosslinkable polymer,

said crosslinkable polymer being crosslinked during elimination of said dispersion medium, or during molding, or after molding, thereby obtaining a crosslinked structure,

wherein the respective zeta potentials of said matrix material and said abrasive are opposite in sign and the difference of said zeta potentials is 5mV or more.

Claim 33 (New): The polishing body according to Claim 32, wherein said dispersion medium is eliminated by spray drying

Claim 34 (New): The polishing body according to Claim 32, wherein the polishing body is adapted for the polishing of semiconductors.